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Comparative Studies of CdZnTe, CdMnTe, and CdZnTeSe Materials for Room-Temperature Nuclear Detection Applications

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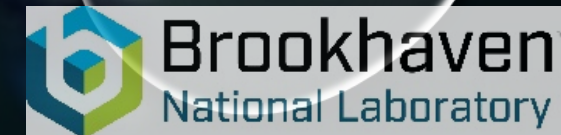
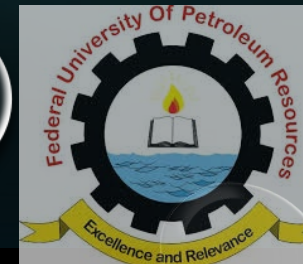
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28th International Symposium on Room-Temperature Semiconductor Detectors

16 - 23 October 2021



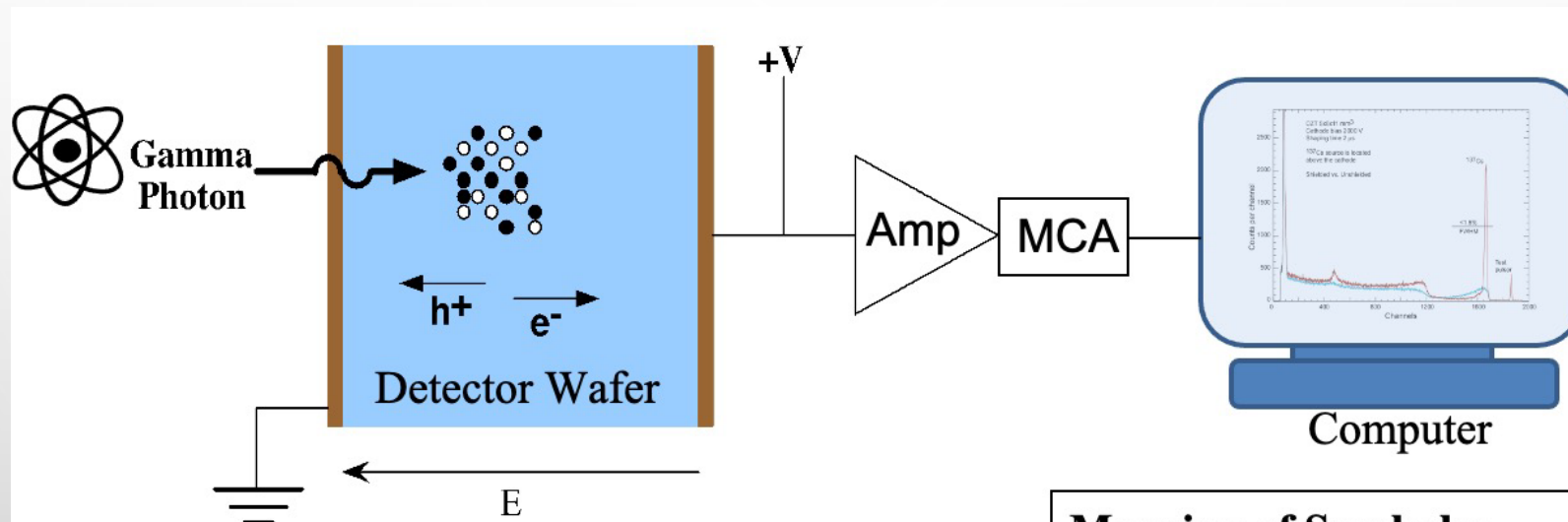
Presentation Outline

- Goals: Review of Our Recent Studies on CdTe-Based Detectors
- Operation of CdTe-Based Detectors
- Device Engineering Design Constraints
- Constant-Temperature Annealing of CdMnTe Detector
- Temperature-Gradient Annealing of CdMnTe Detector
- XPS Study of Passivated CdZnTe Surfaces
- Planar Detector Fabrication
- Electrical Instrumentation for Current-Voltage Measurement
- Surface Chemical Treatments of CdZnTe Detector
- Chemical Passivation of CZTS
- Summary

Goals

- Cadmium telluride (CdTe) and its ternary and quaternary compound have found applications in the development of X-ray and gamma-ray detectors used in medical imaging and in the detection of radiological and nuclear threats.
 - Examples: CdZnTe (CZT), CdMnTe (CMT), and CdZnTeSe (CZTS).
- These detectors can operate at room temperature without cryogenic cooling.
- The goal of this presentation is to review our recent studies of studies of CdTe-based detectors and the effects of **chemical treatments** on their **electrical properties** and **radiation detection performances**.
- The properties to be studied include detector surface species, resistivity, and energy resolution.
- Surface treatment studies include chemo-mechanical polishing and passivation using KOH and NH_4F solutions.

Operation of CdTe-Based Detectors



Basic Operation:

- Gamma rays create electron-hole pairs.
- This creates electrical signal.
- The signal is amplified before the MCA.
- MCA displays the spectrum on the computer screen.

Meaning of Symbols:

e^- : Electron (o).
 h^+ : Hole (•).
V: Applied voltage.
E: Electric field direction.
Amp: Amplifier.
MCA: Multichannel analyzer.

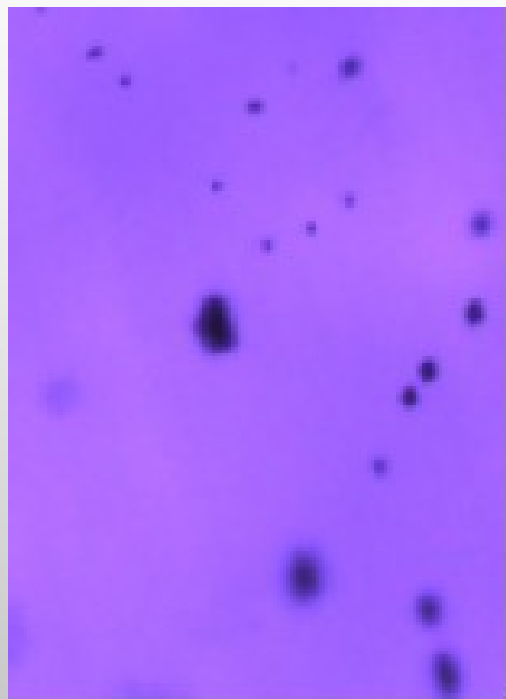
Device Engineering Design Constraints

- High resistivity $> 10^8 \Omega\text{-cm}$.
 - Implies low current. High current could damage the pre-amplifier and amplifier.
- Low surface current (nano-amps). This is required to reduce electronic noise in the generated signal.
- Chemical passivation must result in reduced surface current.
- High charge-carrier mobility-lifetime product.
- Free of defects that affect charge collection and uniformity.
- Low production cost.

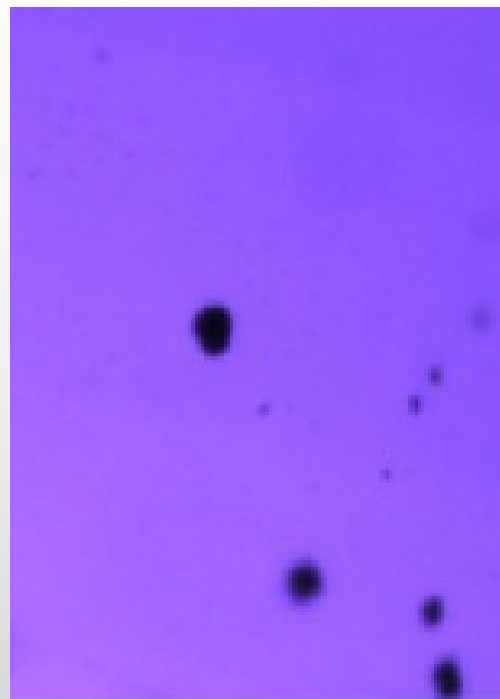
Constant-Temperature Annealing of CdMnTe Detector

- Thermal annealing is used to remove defects caused by Te inclusions in the detector wafer.
- Te inclusions and related defects limit the detector's ability to detect X-rays and gamma-rays.
- Process:
 - The detector wafer is placed together with Cd in a quartz ampoule and sealed in vacuum using a vacuum pump.
 - The ampoule is placed in the furnace region at 720°C for 12 hours.
 - Cd reacts with the excess Te to form a crystalline structure in the wafer, thus reducing the Te inclusions and related defects.

Constant-Temperature Annealing of CdMnTe Detector



(a) Before annealing



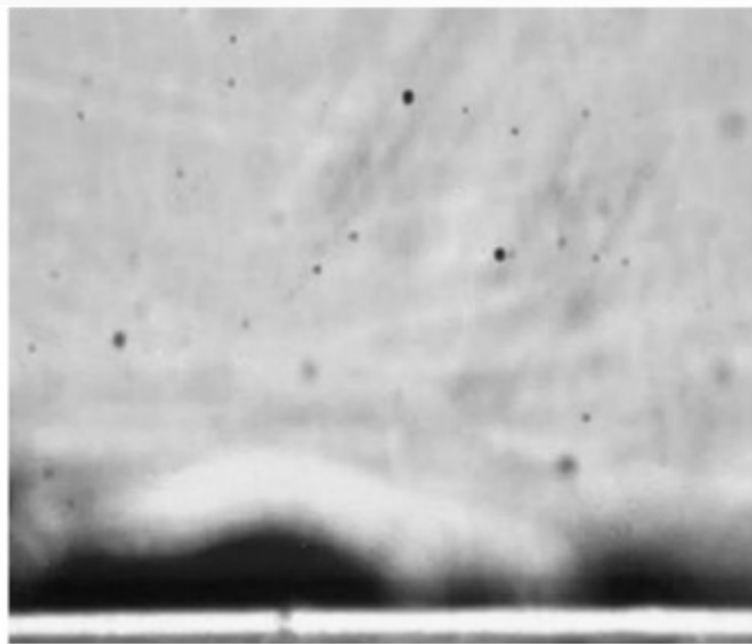
(b) After annealing

Infrared images ($256\ \mu\text{m} \times 367\ \mu\text{m}$) of the same region of the CdMnTe wafer before and after annealing in Cd vapor.



Three-zone annealing furnace (shown on left-side) and vacuum pump (shown on right-side) for removing air when sealing CdMnTe wafers in ampoules.

Constant-Temperature Annealing of CdMnTe Detector



(a) Before annealing.

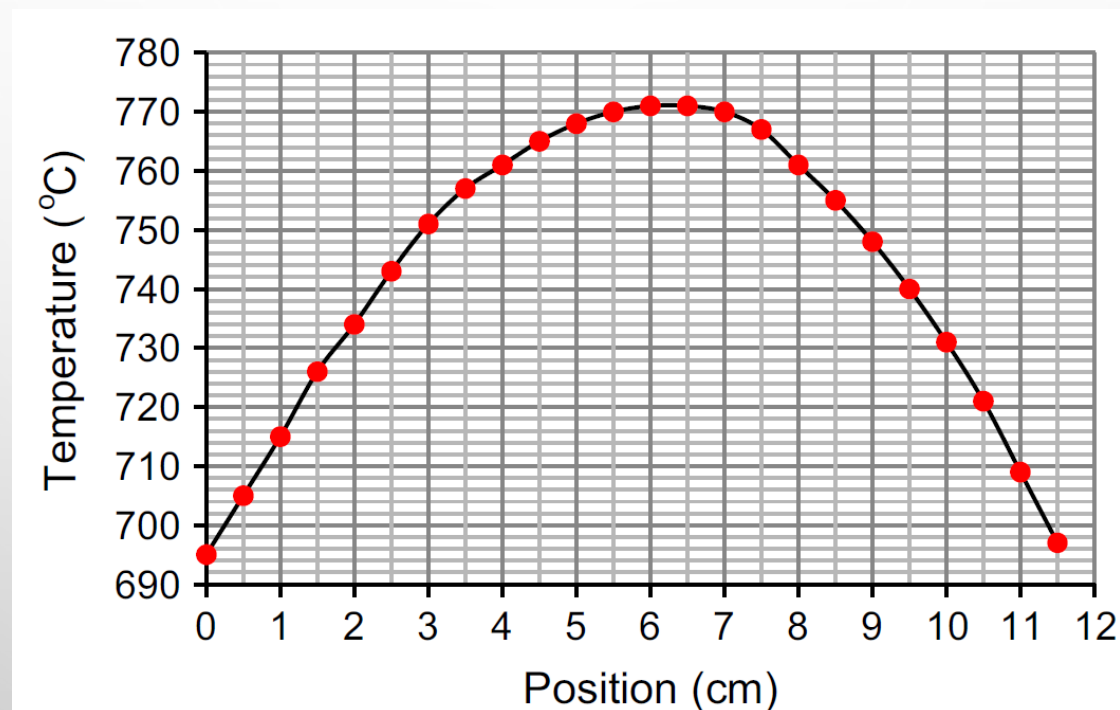


(b) After annealing.

Te inclusions eliminated from a CdMnTe wafer after being annealed at 570°C for 26 hours in Cd vapor.

Source: S. U. Egarievwe, G. Yang, A. A. Egarievwe, A. A., I. O. Okwechime, J. Gray, Z. M. Hales, . . . James, R. B. (2015). Post-growth annealing of Bridgman-grown CdZnTe and CdMnTe crystals for room-temperature nuclear radiation detectors. Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment, 784, 51-55. doi: 10.1016/j.nima.2015.02.006.

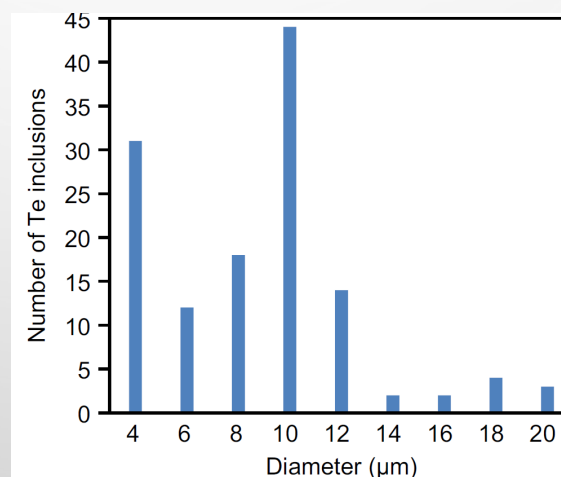
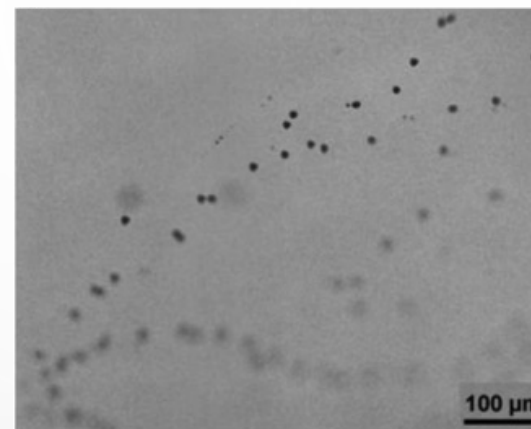
Temperature-Gradient Annealing of CdMnTe Detector



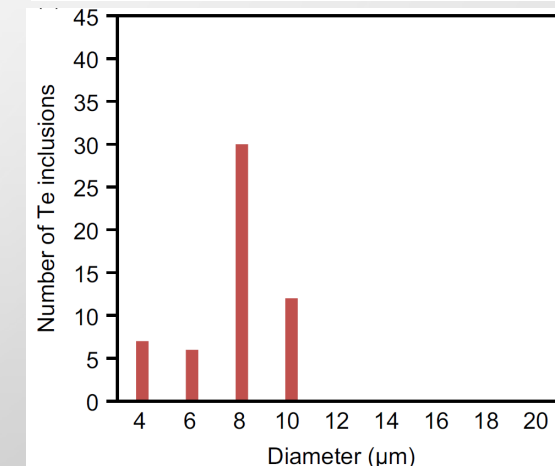
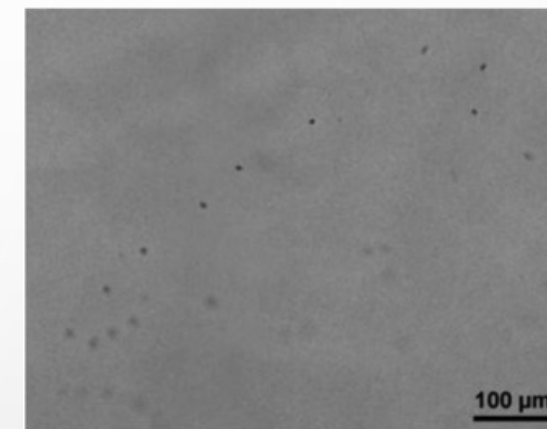
Furnace temperature profile for temperature-gradient annealing.

Temperature-Gradient Annealing of CdMnTe Detector

Size reduction and elimination of Te inclusions in CdMnTe wafer after it was annealed at 730° C for 18 hours at 18°C/cm temperature gradient.



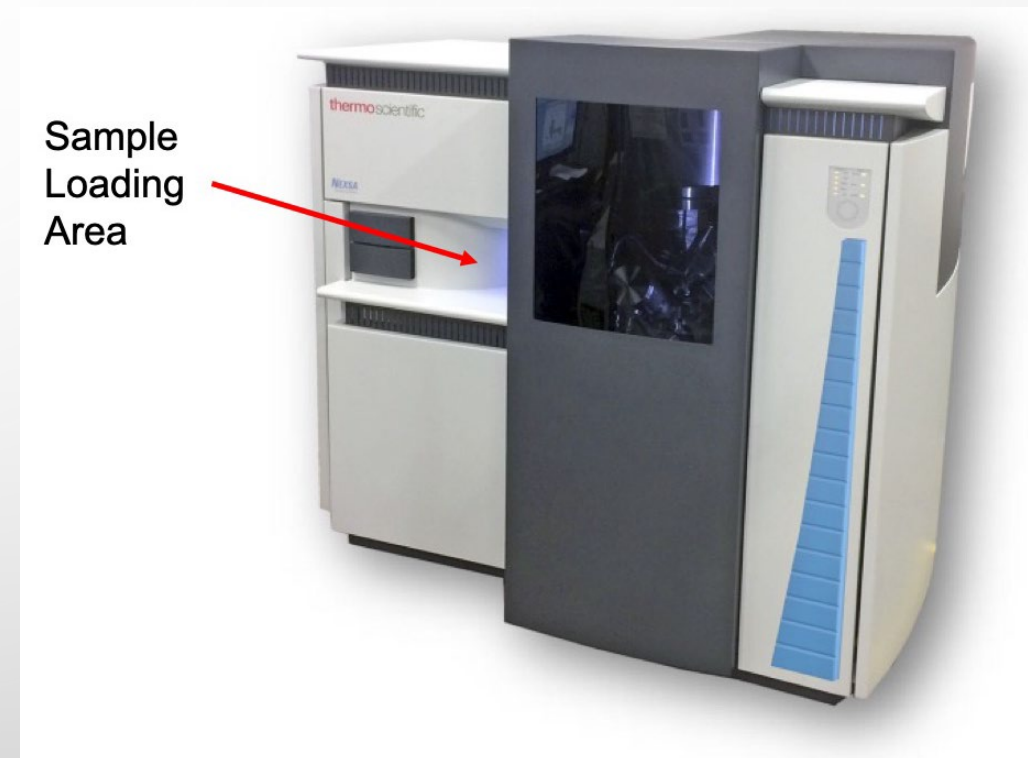
(a) Before annealing.



(b) After annealing.

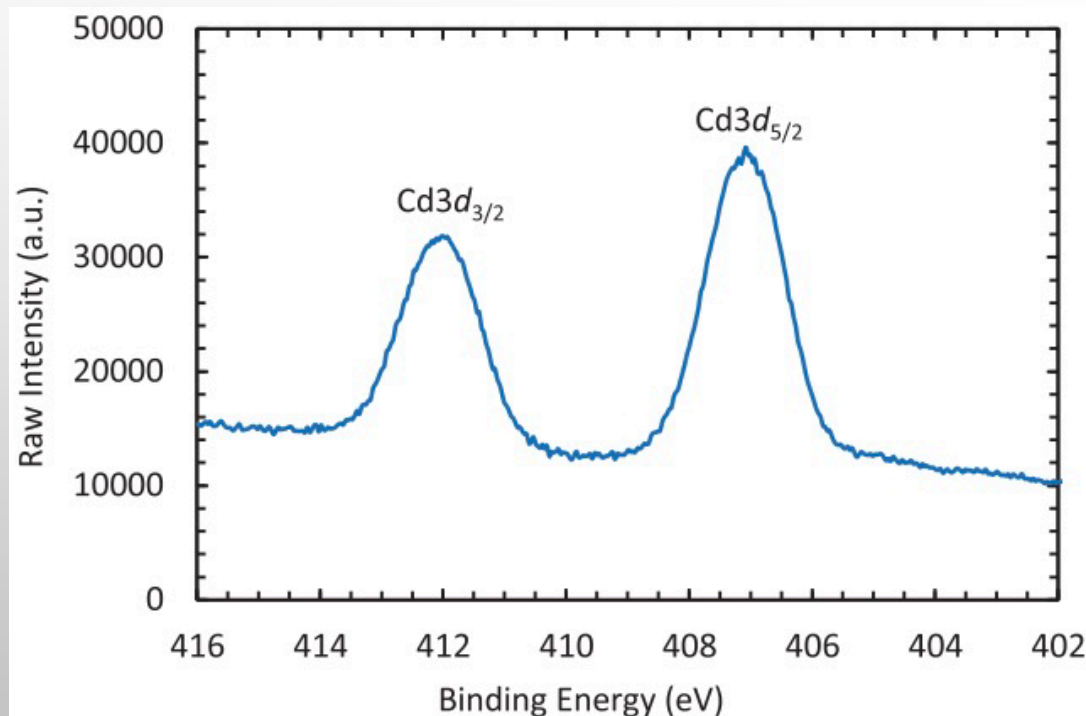
XPS Study of Passivated CdZnTe Surfaces

- Passivation helps to reduce the surface current and improve shelf-life of the device.
- Process: The detector wafer is dipped in the passivation solution and dried with compressed air.
- Chemicals used in Our Studies:
 - A mixture of 0.1 -g potassium hydroxide (KOH) and 10-ml 30% hydrogen peroxide (H_2O_2) aqueous solution.
 - A mixture of ammonium fluoride and 10% hydrogen peroxide in distilled water ($\text{NH}_4\text{F} + \text{H}_2\text{O}_2 + \text{H}_2\text{O}$).

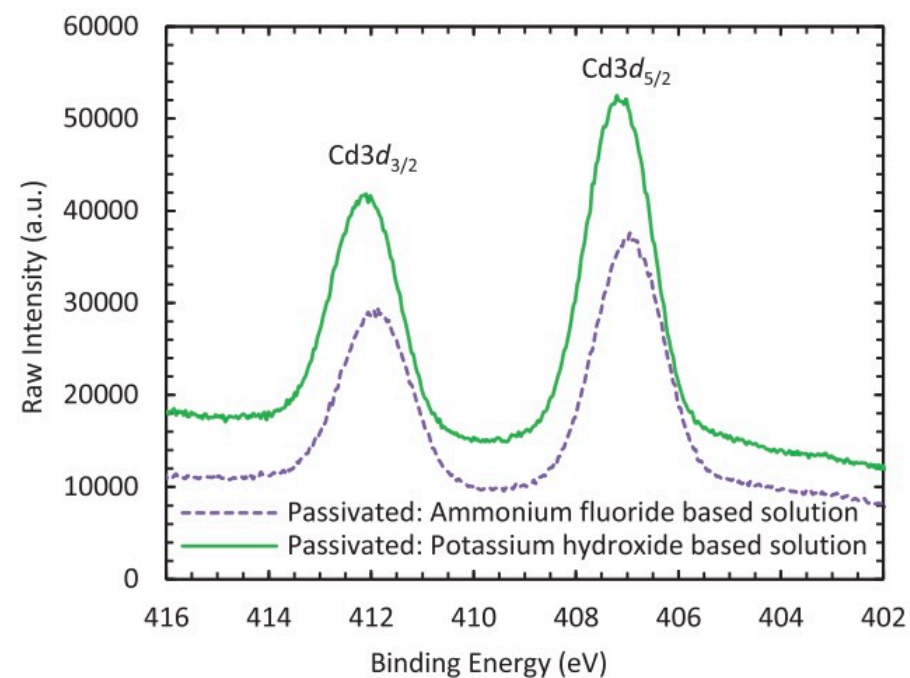


High-performance XPS Surface Analysis
System by Thermo Fisher

XPS Spectra of CdZnTe Surfaces: Cadmium (Cd) Peaks

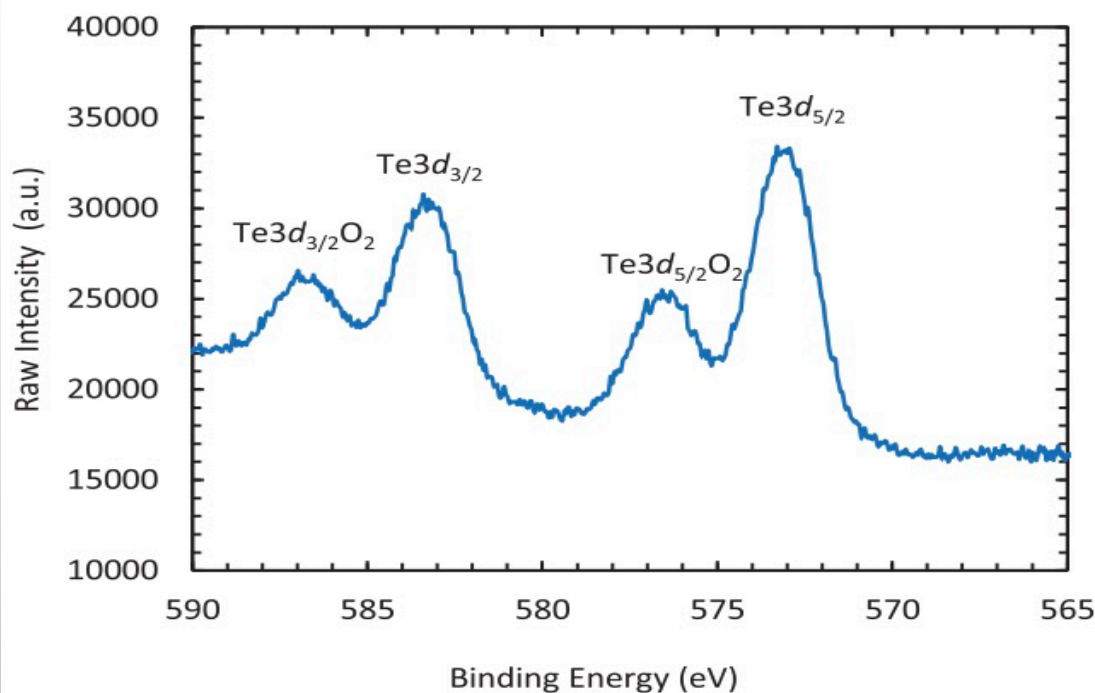


(a) Before passivation.

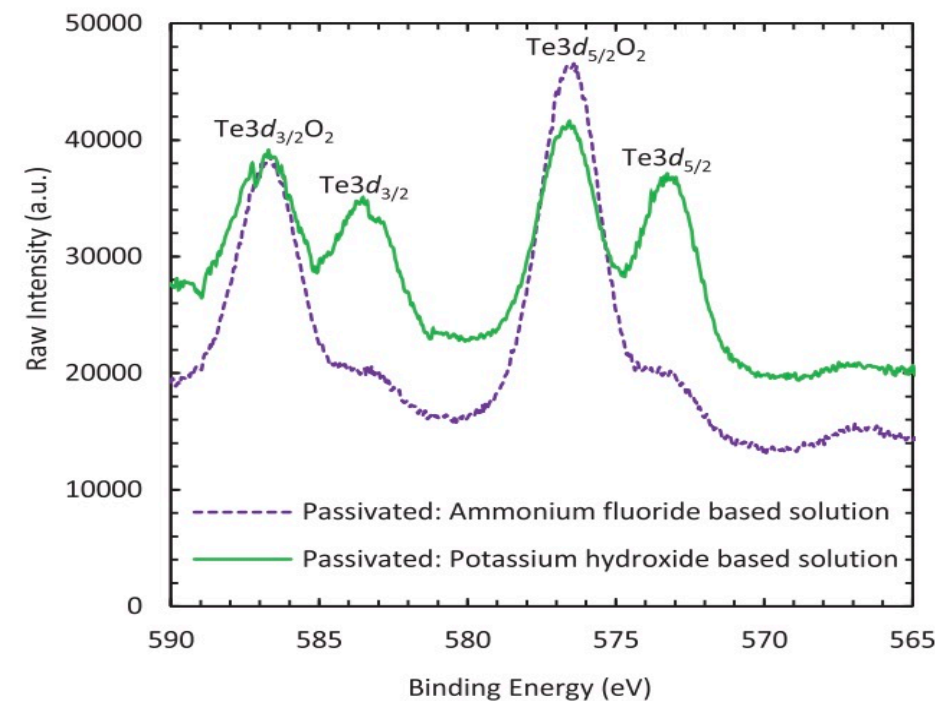


(b) After passivation in KOH, and NH_4F .

XPS Spectra of CdZnTe Surfaces: Te and TeO₂ Peaks



(a) Before passivation.



(b) After passivation in KOH, and NH₄F.

Source: S. U. Egarievwe, A. Hossain, I. Okwechime, A. Egarievwe, D. Jones, Dominique U. Roy, and R. B. James, (2016). Effects of Chemical Treatments on CdZnTe X-Ray and Gamma-Ray Detectors. IEEE Transactions on Nuclear Science. 63. 1091-1098. 10.1109/TNS.2016.2527779.

XPS Spectra of CdZnTe Surfaces: Te and TeO₂ Peaks

Process	Te3d _{3/2} O ₂ /Te3d _{3/2}	Te3d _{5/2} O ₂ /Te3d _{5/2}
Before Passivation	0.49	0.46
After passivation in KOH.	1.25	1.19
After passivation in NH ₄ F.	4.90	5.34

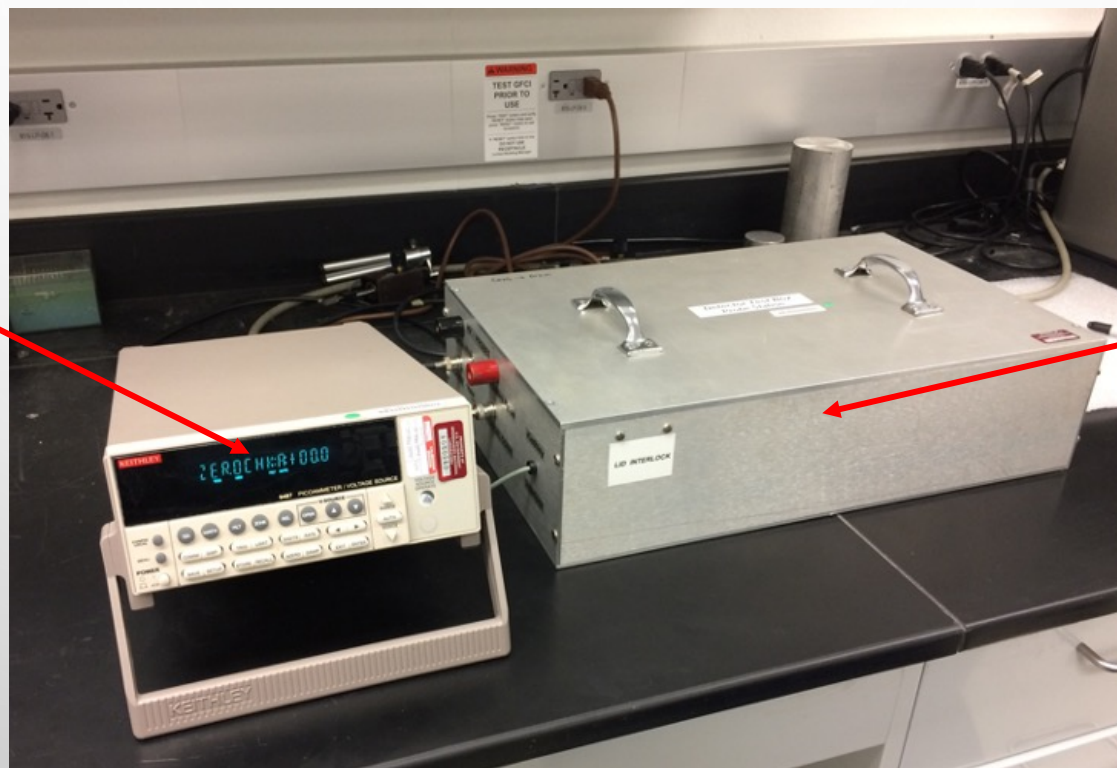
- TeO₂ peaks increased after passivation. This shows the formation more TeO₂.
- Passivation in NH₄F produces more than passivation in KOH.
- Thus, NH₄F is better passivation chemical than KOH.

Planar Detector Fabrication

- Involves four major steps.
 - Wafer Cutting:
 - Cuts detector wafer to desired dimensions using a special cutting machine.
 - Mechanical Polishing:
 - Remove surface defects and residue using silicon-carbide abrasive papers.
 - Chemical Etching and Drying:
 - Used to remove any fine residual damage caused by mechanical polishing.
 - Deposition of Electrical Contacts:
 - Use electroless contact deposition method to deposit electrical contact on two opposite planar surface of the wafer.

Electrical Instrumentation for Current-Voltage Measurement

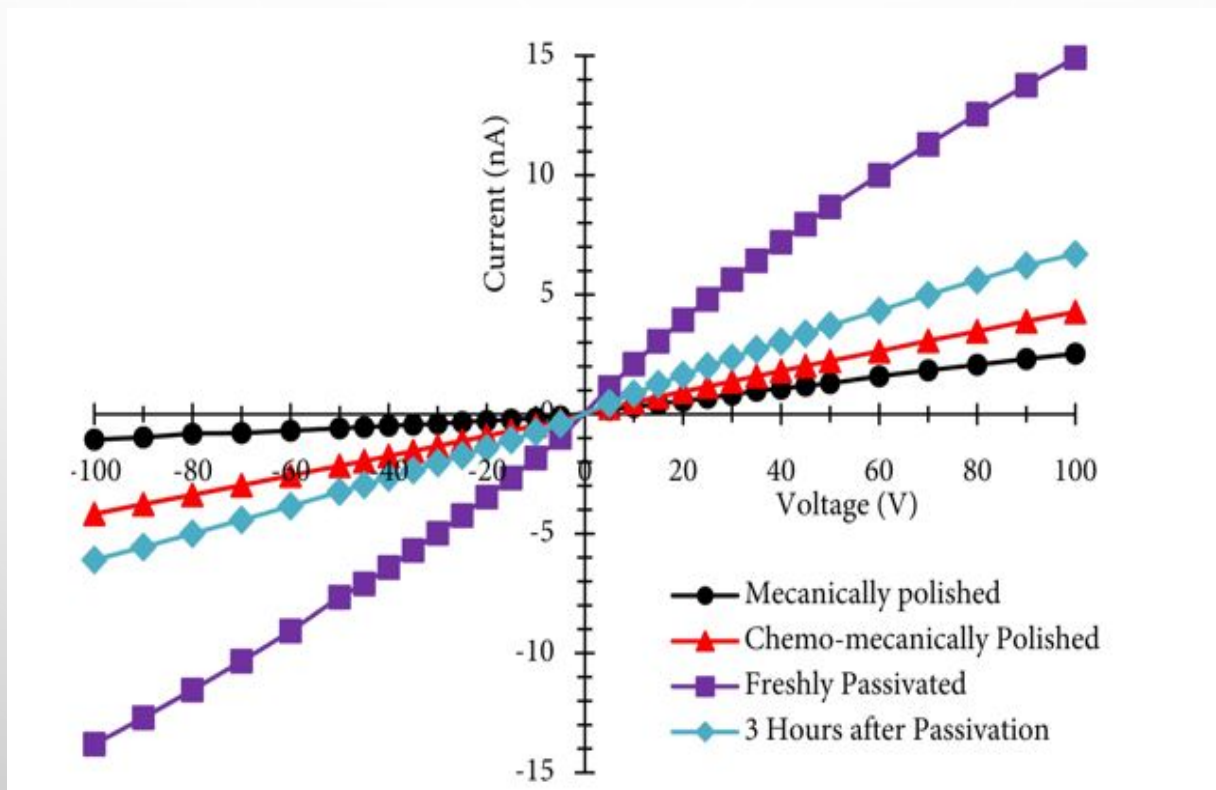
Keithley
Picoammeter/Voltage
Source



Aluminum box
where sample is
mounted

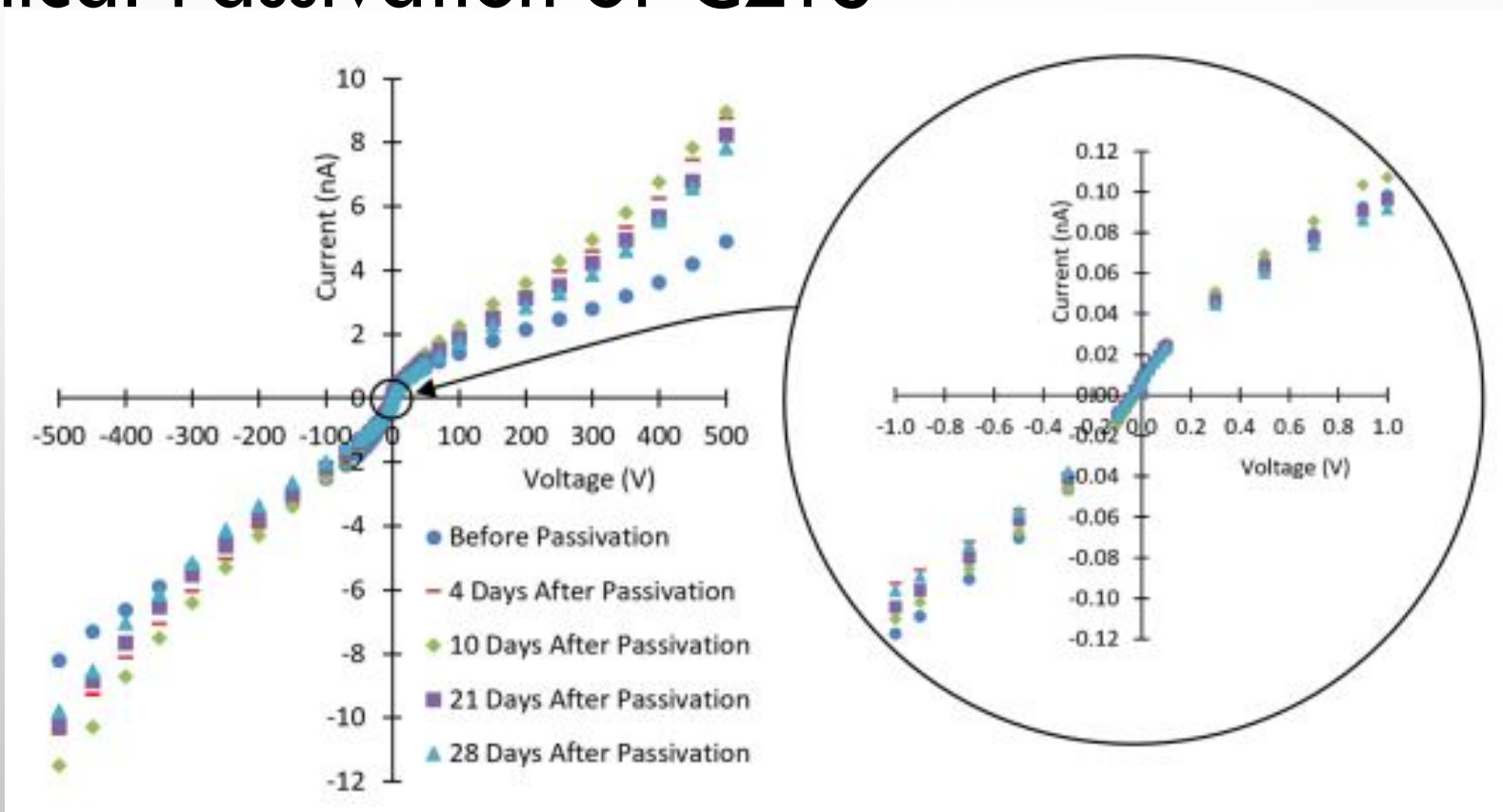
Current-Voltage measurement system at Brookhaven National Laboratory.

Surface Chemical Treatments of CdZnTe Detector



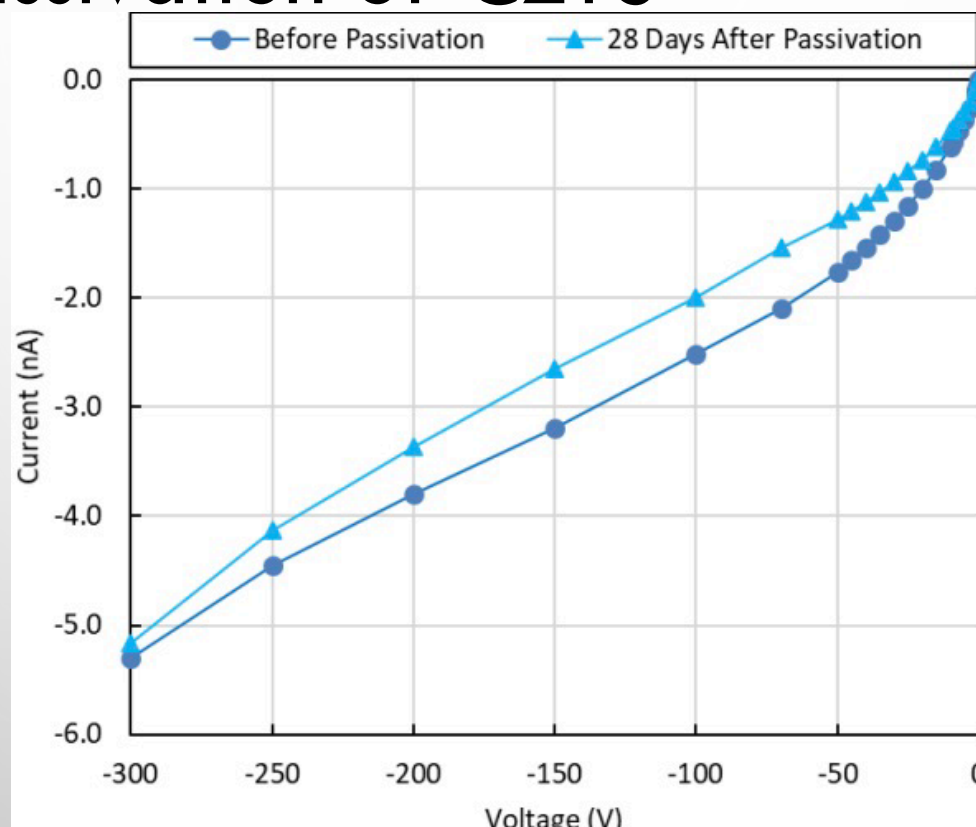
Current-voltage plots for different surface chemical treatments of CdZnTe.

Chemical Passivation of CZTS



Current-Voltage plots that show passivation results after different days.

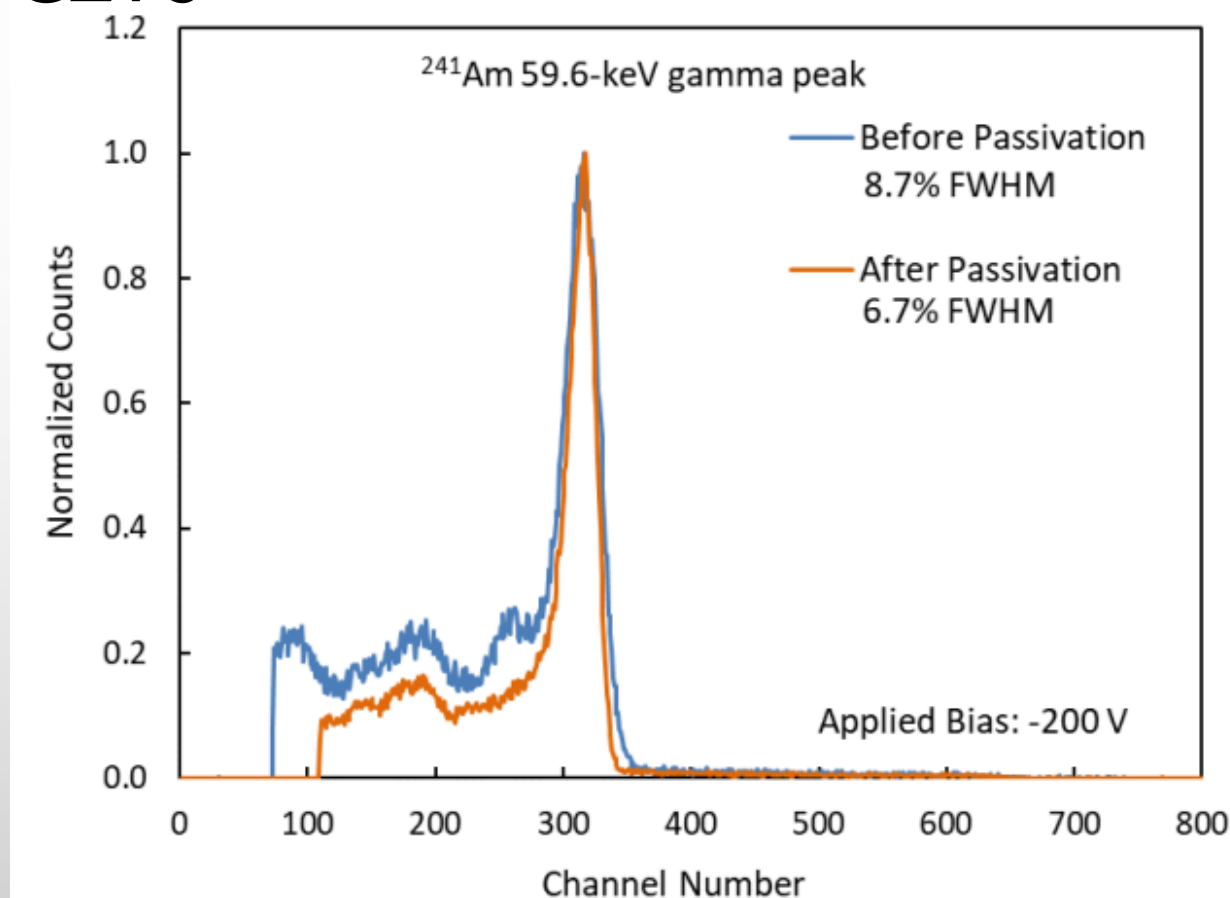
Chemical Passivation of CZTS



Voltage regions with reduced current 28 days after passivation.

Chemical Passivation of CZTS

CZTS detector response from a ^{241}Am source at -200V before passivation and 28 days after passivation.



Summary

- Thermal annealing reduces the sizes and concentrations of Te inclusions.
- XPS studies of passivated samples showed that:
 - TeO_2 formation increased after passivation.
 - NH_4F is better passivation chemical agent than KOH .
- Passivation in NH_4F improves energy resolution.

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Thank You